<u>List of symbols and abbreviations</u>

PART I

a,b,c : Latticce paramters of unit cell

C : Intercept of line on Y-axis

d-AHT : Ammonium hydrogen d-tartarate crystal

 d_{hkl} : Interplanar spacing of (hkl) planes

F : Feed solution

M : Molarity

m : Slope of straight line plot

m₁ : Regression coefficient of y on x

m2 : Regression coefficient of x on y

N : Normality

r : Correlation coefficient

W ' Molecular Weight

x : mean (average) value

y : mean (average) value

o : Temperature in °C

d0 : temperature difference

? : density of d-AHT

e : density of kerosene

PART II & III

A : area of cross section: angle of orientation of the linger diagonal of the Knoop indentation mark measured with respect to the specified direction

 $A_{\rm O}$: initial area of cross-section

a : standard hardness (constant)

Ap : axis of rotation

. b : constant

c : constant : constant of indenter geometry

d : diagonal length of Knoop indentation mark

E : Young's modulus of elasticity

e,f : constant

F : Free, face (facet)

H : average hardness in high load region

HLR : high load region

ho : minimum value of hardness in the quadratic equation of $\mbox{\tt H}$

Vs A

ILR : intermediate load region

K : constant

1 : length after small compression

lo : initial length

LLR : low load region

n : slope of the plot of log d vs log P

n₁: slope of the plot of log d vs log P in LLR

 n_2 : slope of the plot of log d vs log P in HLR

P : load in gms; constant

r : constant of indenter geometry

RT : Room temperature

SMS : Sodium metasilicate solution

Sp.gr. : Specific gravity

t : time

T : absolute temperature

TA : tartaric acid solution

W : Newtonian resistance pressure

0 : Bragg angle

i : path difference

d : wavelength of x-ray beam

6 : compressive stress

€ : compressive strain

PART IV

B : breadth of an etch pit

C : concentration of an etchant

E : activation energy

Et : activation energy for tangential dissolution

 E_{S} : activation energy for surface dissolution

K : Boltzmann constant :

L : Length of an etch-pit

R : Universal gas constant

V : rate of dissolution

 V_{t} , : lateral/tangential or ledge dissolution velocity

V_I: parallel to the surface

 V_n : dissolution velocity normal to surface

V_B : rate of surface dissolution

 V_{nd} : normal dissolution velocity at a dislocation

 v_{ndf} : normal dissolution velocity of a dislocation-free

portion of the surface